



**XYD065N85**

**85V N-channel Shielding Gate MOSFET**

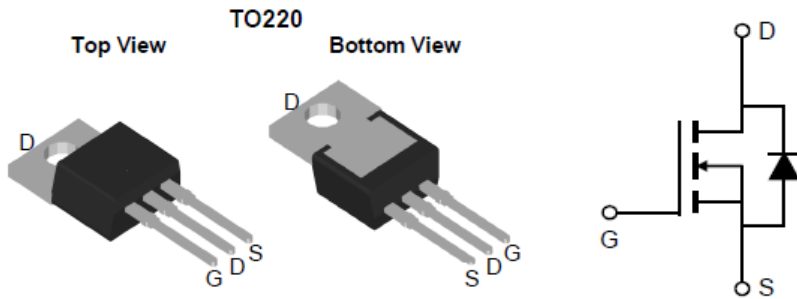
XYD065N85

**Features**

- N-channel, normal level
- Excellent Gate charge  $\times R_{DS(on)}$  (FOM)
- Very low on-resistance  $R_{DS(on)}$

**This chip is used for:**

- Industrial power supplies
- Boost converters
- Rectifier
- Telecom
- Industrial power supplies



Symbol	Parameter	Value	Units
V <sub>DS</sub>	Drain-Source Voltage	85	V
I <sub>D</sub>	Drain Current - Continuous (TC= 25°C)	110	A
	Drain Current - Continuous (TC= 100°C)	72	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	200	A
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	136	mJ
P <sub>D</sub>	Power Dissipation (TC = 25°C)	162	W
T <sub>j</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range	-55 to +175	°C

\* Drain current limited by maximum junction temperature

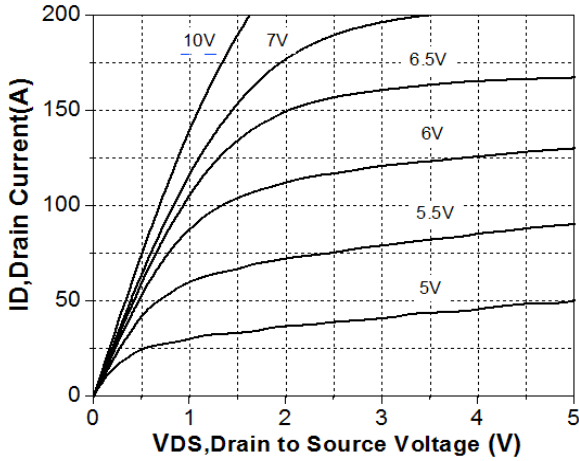
**Thermal Characteristics**

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	0.60	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	50	°C/W

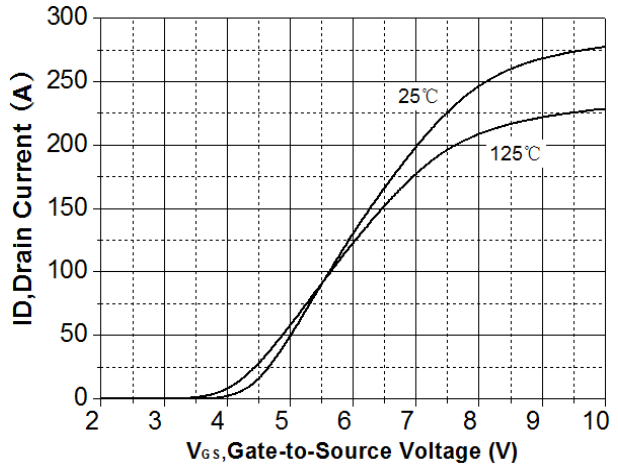
Electrical Characteristics <small>TC = 25°C unless otherwise noted</small>						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	85			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 85\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate Leakage Current	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA
<b>On Characteristics</b>						
$V_{GS(TH)}$	Gate Threshold voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	2.5	3	3.5	V
$R_{DS(on)}$	Drain-Source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 50\text{ A}$		6	6.5	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 50\text{ A}$ (Note 3)		83		S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input capacitance	$V_{GS}=0\text{V},$		2226		pF
$C_{oss}$	Output capacitance	$V_{DS}=40\text{V},$		463		pF
$C_{rss}$	Reverse transfer capacitance	$f=1\text{MHz}$		12		pF
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn On Delay Time	$V_{DS} = 40\text{ V}, I_D = 50\text{ A},$ $V_{GS} = 10\text{ V}, R_G = 4.7\ \Omega$ (Note 3, 4)		19		ns
$t_r$	Rising Time			33		ns
$t_{d(off)}$	Turn Off Delay Time			29		ns
$t_f$	Fall Time			19		ns
$Q_g$	Total Gate Charge	$V_{DS} = 40\text{ V}, I_D = 50\text{ A},$ $V_{GS} = 10\text{ V}$ (Note 3, 4)		38		nC
$Q_{gs}$	Gate-Source Charge			6		nC
$Q_{gd}$	Gate-Drain Charge			19		nC
$R_g$	Gate Resistance	$V_{DS} = 0\text{ V}, \text{Scan F mode}$		2.3		$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 100\text{A}$			1.2	V
$T_{rr}$	Reverse recovery time	$I_S=50\text{A}, V_{GS} = 0\text{V},$ $di_F/dt = 100\text{A/us}$		37		ns
$Q_{rr}$	Reverse recovery charge			31		nC
<b>Notes:</b> 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. $L = 0.5\text{ mH}, I_{AS} = 28\text{ A}, V_{DD} = 10\text{V}, R_G = 25\ \Omega,$ Starting $T_j = 25^\circ\text{C}$ 3. $I_{SD} \leq 40\text{A}, di/dt = 100\text{A/us}, V_{DD} \leq BV_{DSS},$ Starting $T_j = 25^\circ\text{C}$ 4. Pulse Test : Pulse width $\leq 300\text{us},$ Duty cycle $\leq 2\%$ 5. Essentially independent of operating temperature						

**Typical Electronic and Thermal Characteristics**

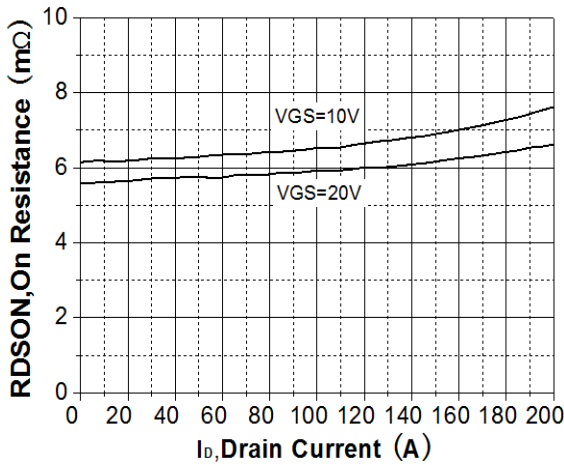
**Table 7 Reverse diode characteristics**



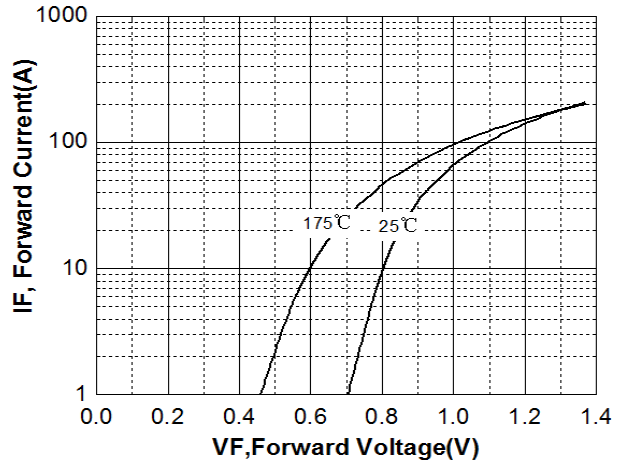
**Figure 1. On-Region Characteristics**



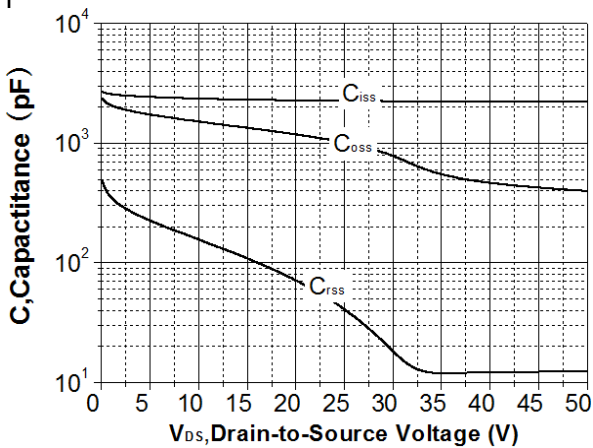
**Figure 2. Transfer Characteristics**



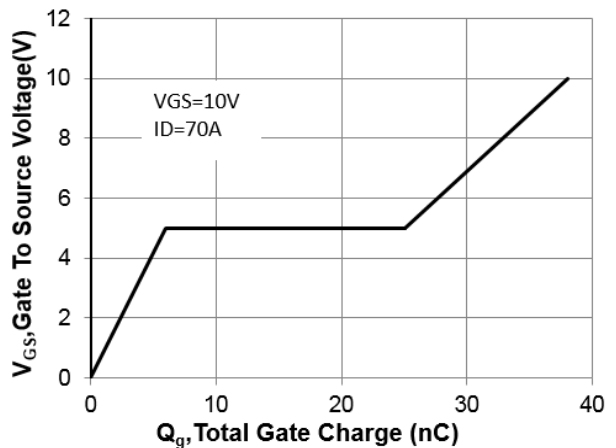
**Figure 3. On-Resistance Variation vs Drain Current**



**Figure 4. Body Diode Forward Voltage Vs Reverse Drain Current**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**

Typical Electronic and Thermal Characteristics

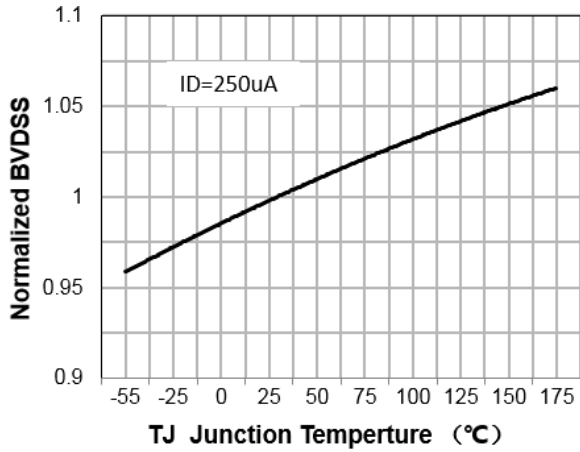


Figure 7. Breakdown Voltage Variation vs Temperature

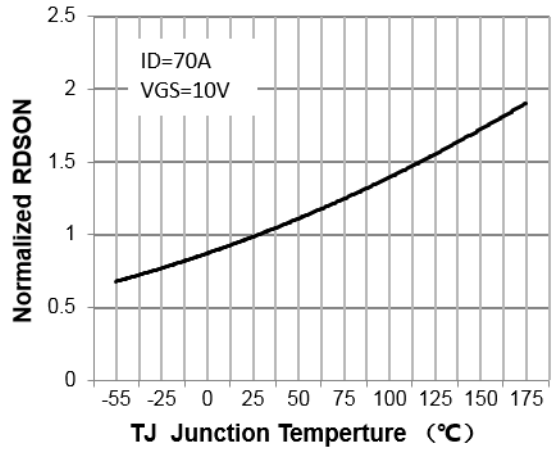


Figure 8. On-Resistance Variation vs Temperature

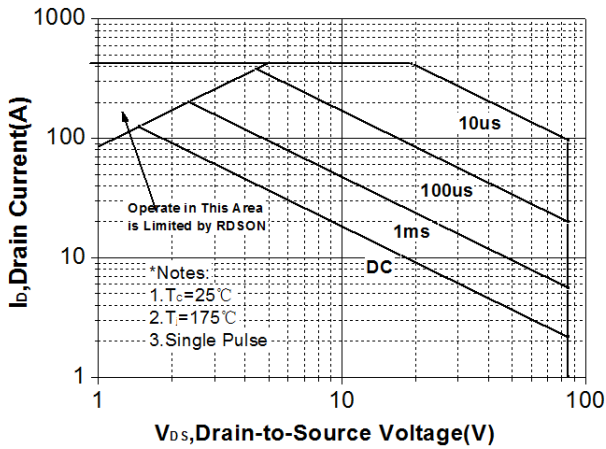


Figure 9. Maximum Safe Operating Area

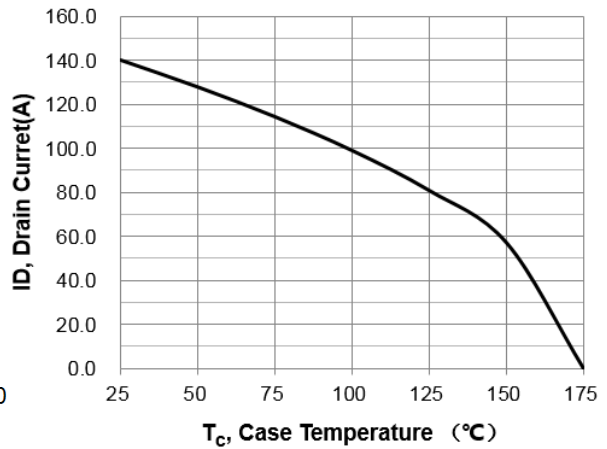


Figure 10. Maximum Drain Current vs Case Temperature

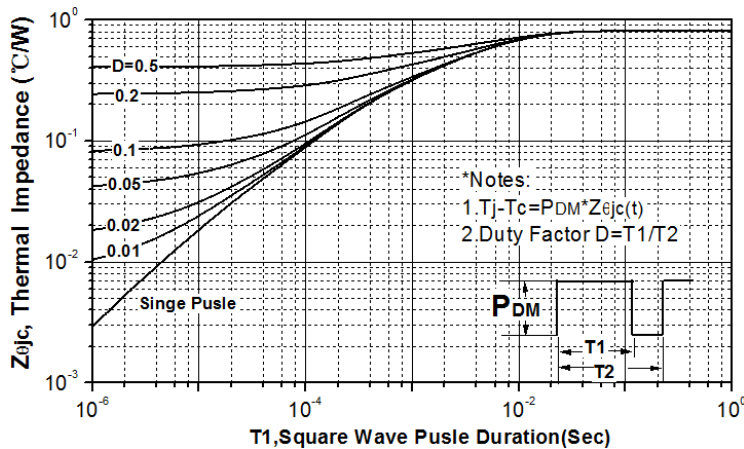
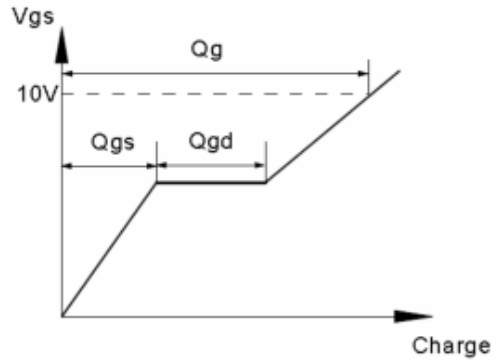
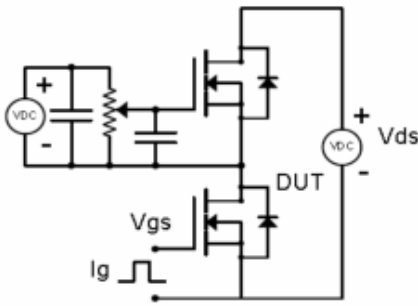


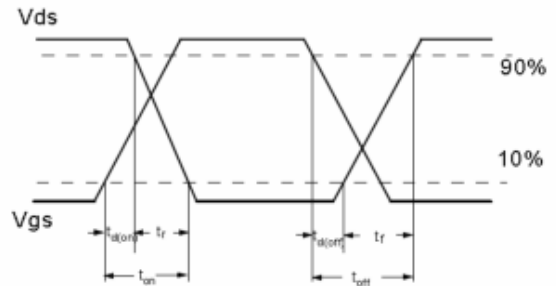
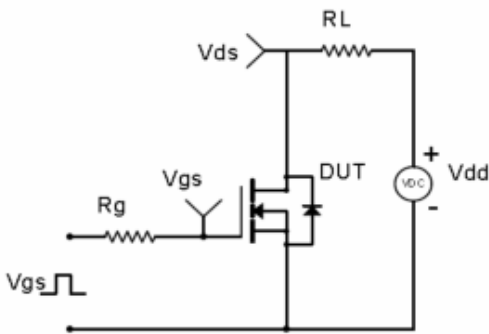
Figure 11. Transient Thermal Response Curve

**Test Circuit & Waveform**

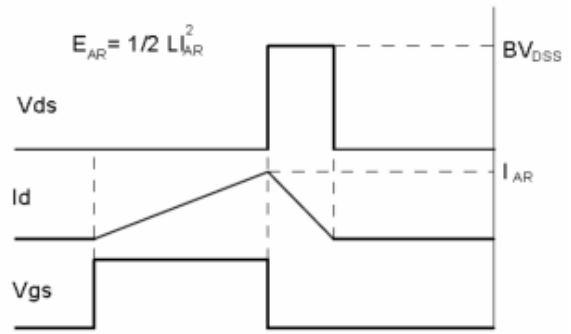
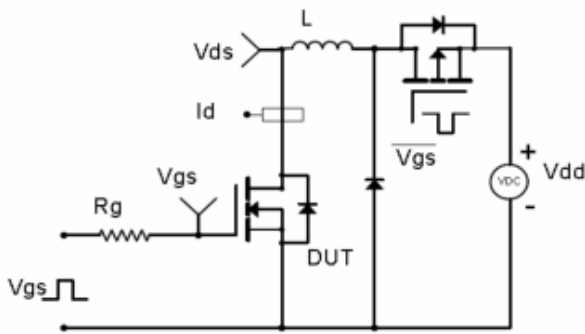
Gate Charge Test Circuit & Waveform



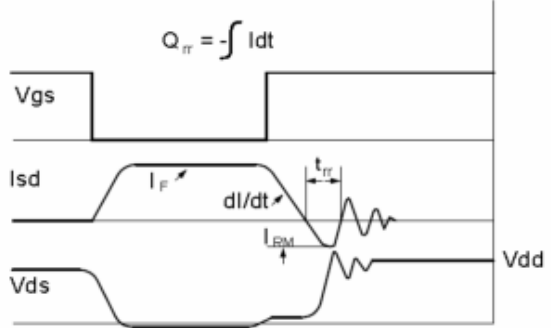
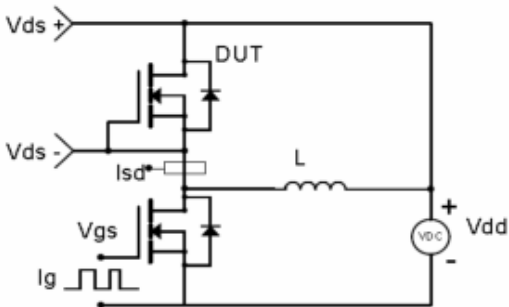
Resistive Switching Test Circuit & Waveforms



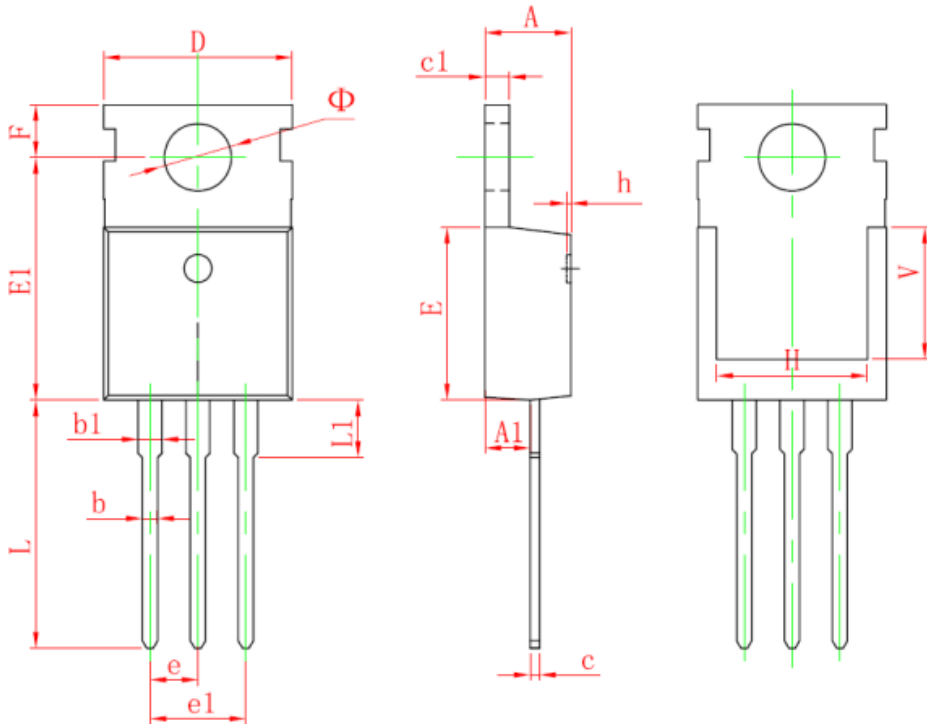
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



### Package Dimensions : TO-220-3L(T0.5mm) PACKAGE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
$\Phi$	3.400	3.800	0.134	0.150